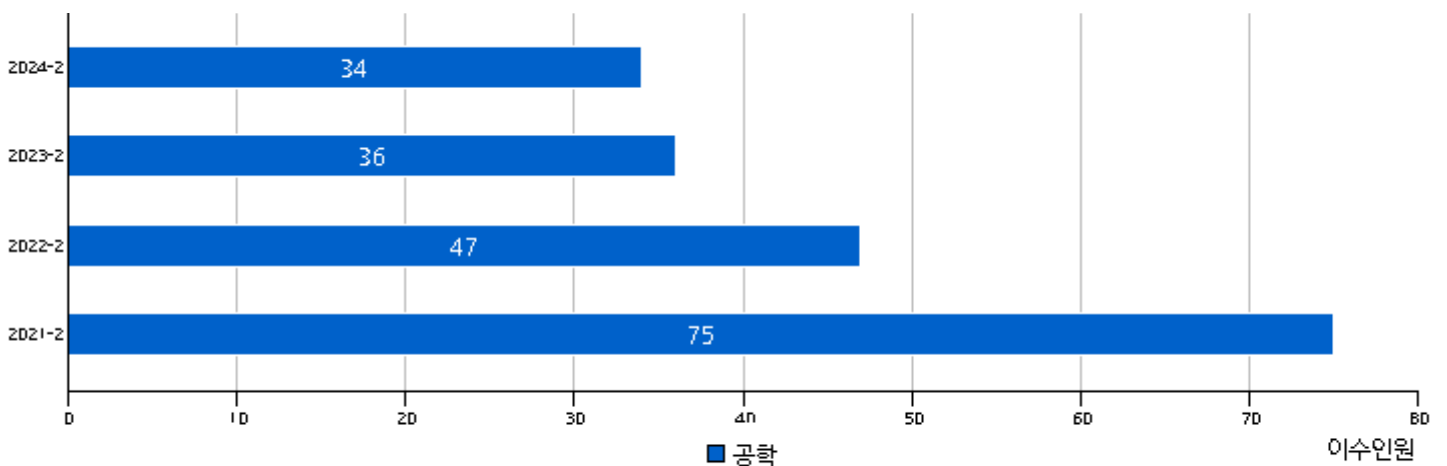
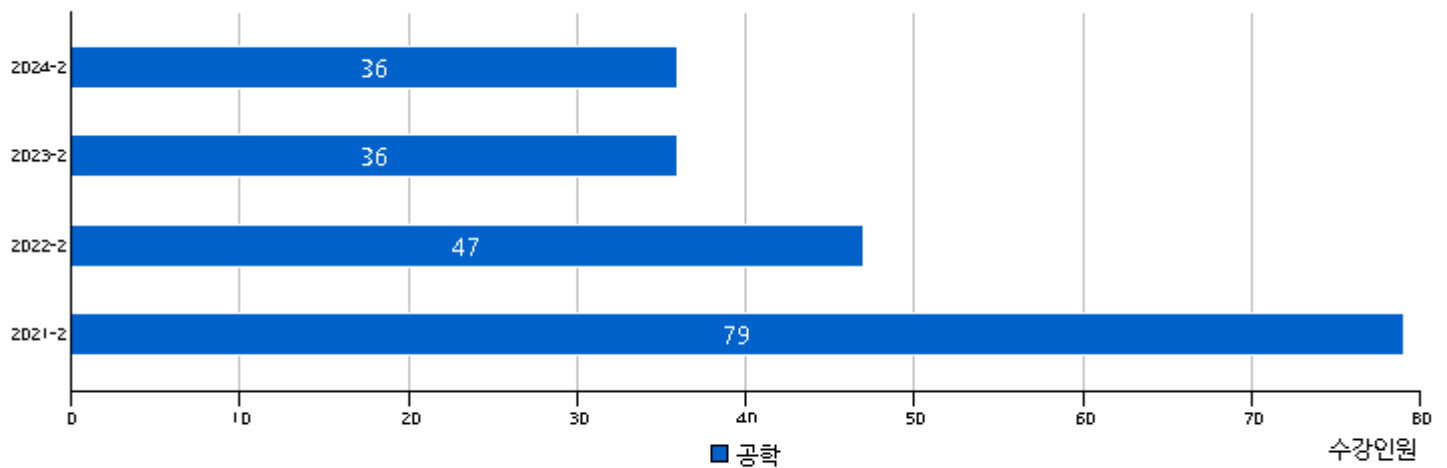
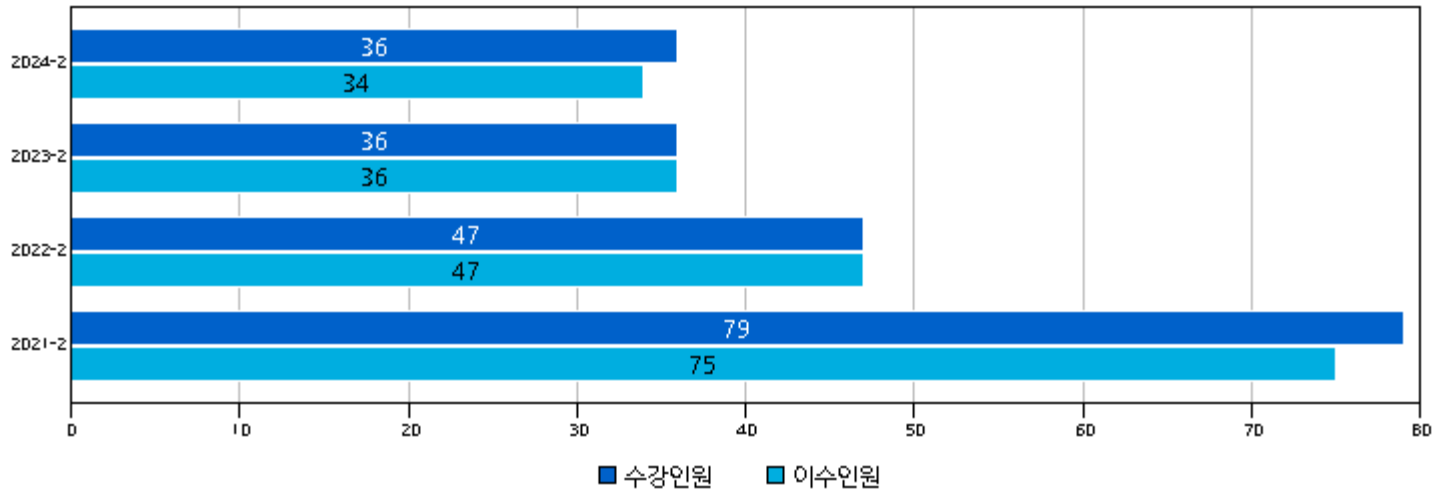


교과목 포트폴리오 (MEE4088 반도체및MEMS공정개론)

1. 교과목 수강인원



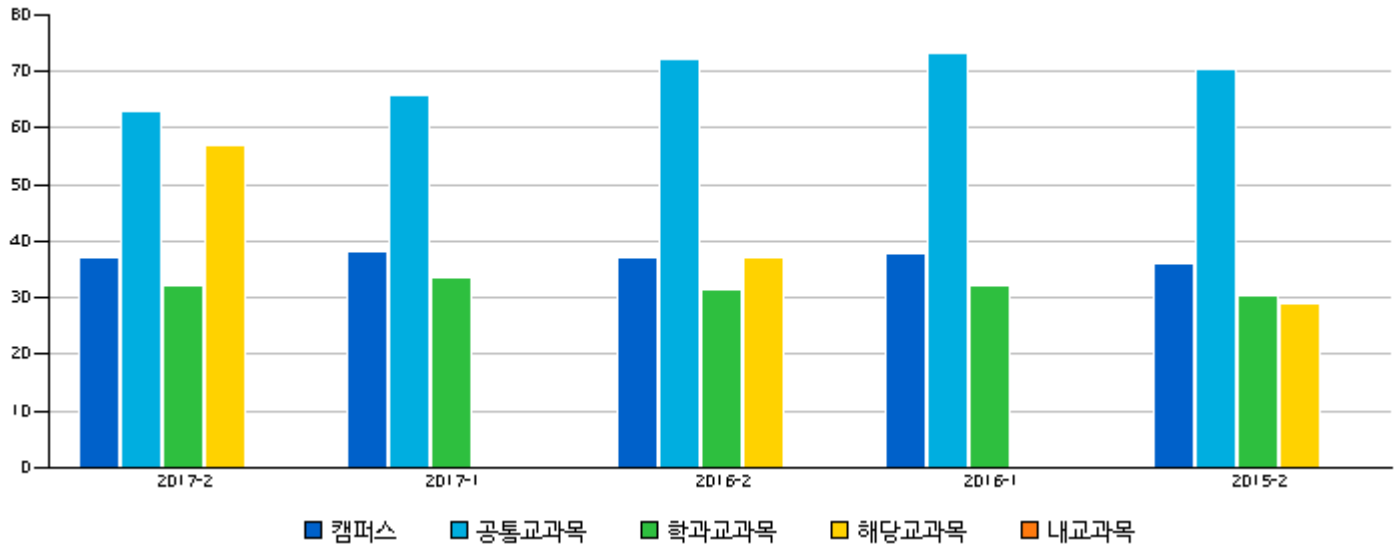
교과목 포트폴리오 (MEE4088 반도체및MEMS공정개론)

수업년도	수업학기	계열구분	수강인원	이수인원
2021	2	공학	79	75
2022	2	공학	47	47
2023	2	공학	36	36
2024	2	공학	36	34



교과목 포트폴리오 (MEE4088 반도체및MEMS공정개론)

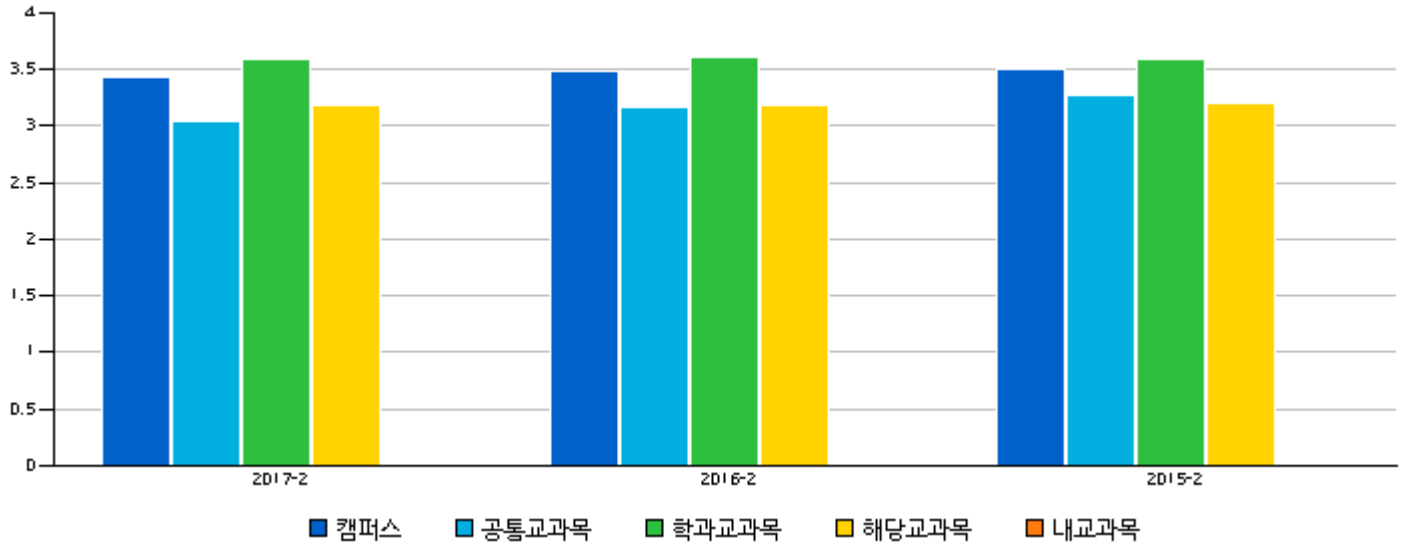
2. 평균 수강인원



수업년도	수업학기	캠퍼스	공통교과목	학과교과목	해당교과목	내교과목
2017	2	37.26	63.09	32.32	57	
2017	1	38.26	65.82	33.5		
2016	2	37.24	72.07	31.53	37	
2016	1	37.88	73.25	32.17		
2015	2	36.28	70.35	30.36	29	

교과목 포트폴리오 (MEE4088 반도체및MEMS공정개론)

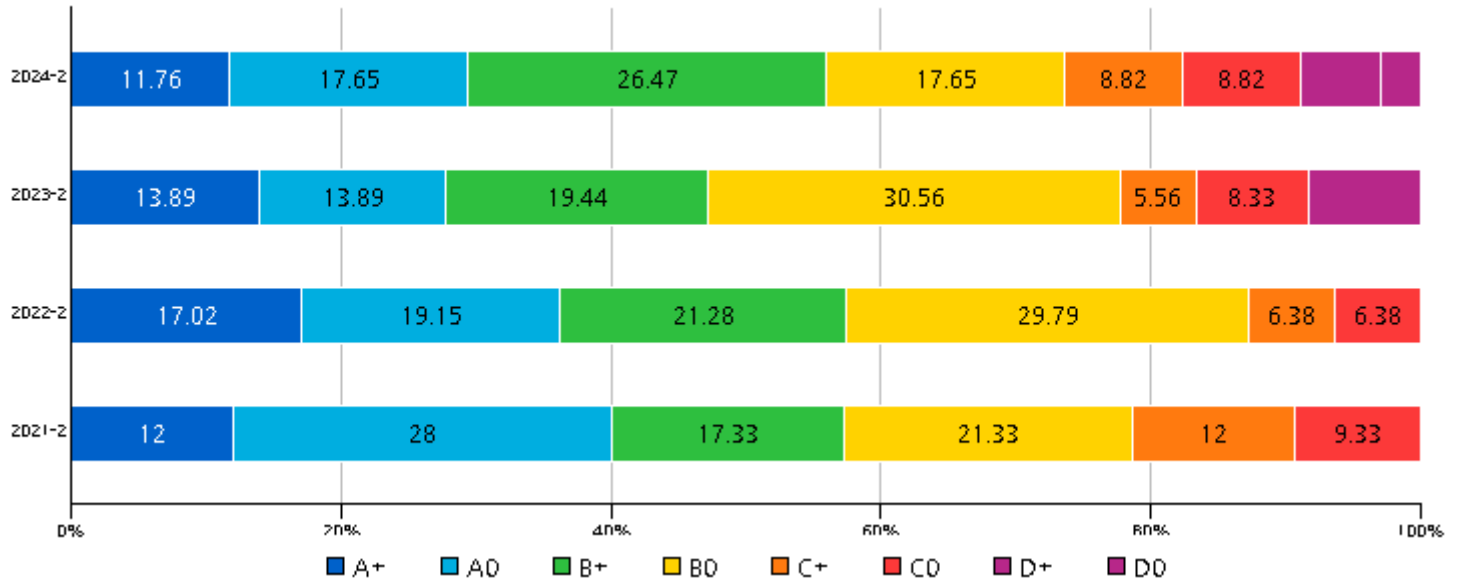
3. 성적부여현황(평점)



수업년도	수업학기	캠퍼스	공통교과목	학과교과목	해당교과목	내교과목
2017	2	3.44	3.05	3.59	3.19	
2016	2	3.49	3.16	3.61	3.19	
2015	2	3.51	3.28	3.6	3.21	

교과목 포트폴리오 (MEE4088 반도체및MEMS공정개론)

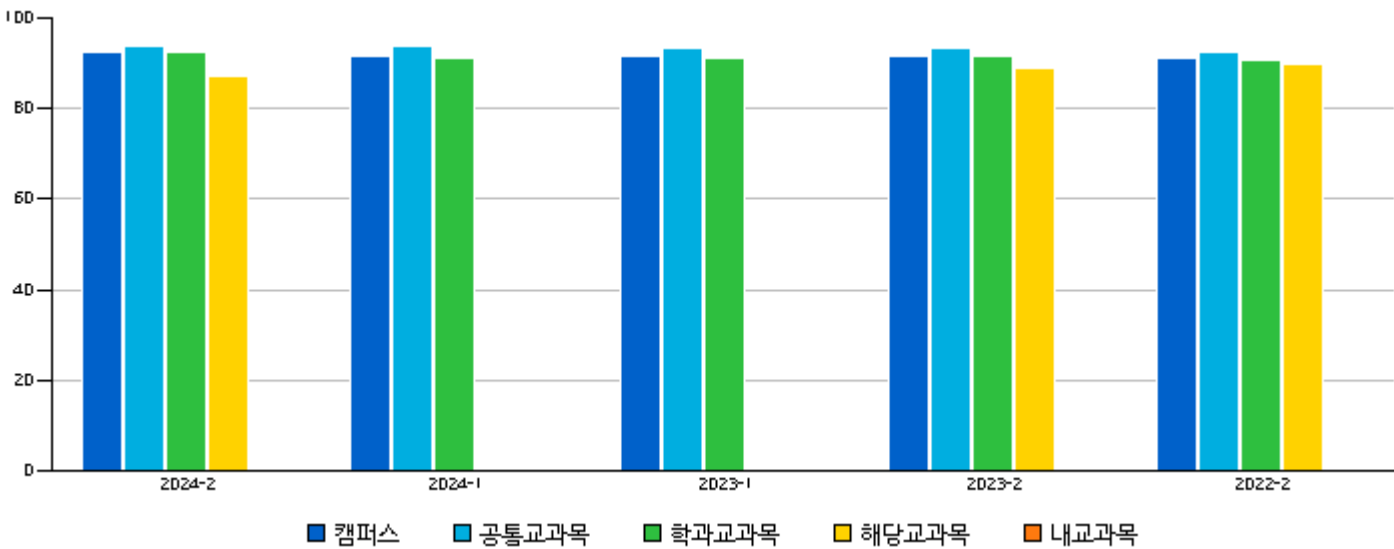
4. 성적부여현황(등급)



수업년도	수업학기	등급	인원	비율	수업년도	수업학기	등급	인원	비율
2021	2	A+	9	12	2024	2	A0	6	17.65
2021	2	A0	21	28	2024	2	B+	9	26.47
2021	2	B+	13	17.33	2024	2	B0	6	17.65
2021	2	B0	16	21.33	2024	2	C+	3	8.82
2021	2	C+	9	12	2024	2	C0	3	8.82
2021	2	C0	7	9.33	2024	2	D+	2	5.88
2022	2	A+	8	17.02	2024	2	D0	1	2.94
2022	2	A0	9	19.15					
2022	2	B+	10	21.28					
2022	2	B0	14	29.79					
2022	2	C+	3	6.38					
2022	2	C0	3	6.38					
2023	2	A+	5	13.89					
2023	2	A0	5	13.89					
2023	2	B+	7	19.44					
2023	2	B0	11	30.56					
2023	2	C+	2	5.56					
2023	2	C0	3	8.33					
2023	2	D+	3	8.33					
2024	2	A+	4	11.76					

교과목 포트폴리오 (MEE4088 반도체및MEMS공정개론)

5. 강의평가점수



수업년도	수업학기	캠퍼스	공통교과목	학과교과목	해당교과목	내교과목
2024	2	92.56	93.8	92.33	87	
2024	1	91.5	93.79	91.1		
2023	1	91.47	93.45	91.13		
2023	2	91.8	93.15	91.56	89	
2022	2	90.98	92.48	90.7	90	

교과목 포트폴리오 (MEE4088 반도체및MEMS공정개론)

6. 강의평가 문항별 현황

번호	평가문항	본인평균 (가중치적용)	소속학과, 대학평균과의 차이 (+초과, -:미달)				점수별 인원분포				
							매우 그렇 않 다	그 렇 지 않 다	보 통 이 다	그 렇 다	매우 그 렇 다
		5점 미만	학과		대학		1점	2점	3점	4점	5점
			차이	평균	차이	평균					
	교강사:										

No data have been found.

7. 개설학과 현황

학과	2025/2	2024/2	2023/2	2022/2	2021/2
기계공학부	1강좌(3학점)	1강좌(3학점)	1강좌(3학점)	1강좌(3학점)	1강좌(3학점)

8. 강좌유형별 현황

강좌유형	2021/2	2022/2	2023/2	2024/2	2025/2
일반	1강좌(79)	1강좌(47)	1강좌(36)	1강좌(36)	0강좌(0)

9. 교과목개요

교육과정	관장학과	국문개요	영문개요	수업목표
학부 2024 - 2027 교육과 정	서울 공과대학 기계공학부	This lecture will cover the processing techniques and design methodologies of microfabrication. We will discuss the process modules: lithography, thermal oxidation, diffusion, ion implantation, etching, thin-film deposition, epitaxy, metallization, MEMS process integration.	This lecture will cover the processing techniques and design methodologies of microfabrication. We will discuss the process modules: lithography, thermal oxidation, diffusion, ion implantation, etching, thin-film deposition, epitaxy, metallization, MEMS process integration.	
학부 2020 - 2023 교육과 정	서울 공과대학 기계공학부	This lecture will cover the processing techniques and design methodologies of microfabrication. We will discuss the process modules: lithography, thermal oxidation, diffusion, ion implantation, etching, thin-film deposition, epitaxy, metallization, MEMS process integration.	This lecture will cover the processing techniques and design methodologies of microfabrication. We will discuss the process modules: lithography, thermal oxidation, diffusion, ion implantation, etching, thin-film deposition, epitaxy, metallization, MEMS process integration.	
학부 2016 - 2019 교육과 정	서울 공과대학 기계공학부	This lecture will cover the processing techniques and design methodologies of microfabrication. We will discuss the process modules: lithography, thermal oxidation, diffusion, ion implantation,	This lecture will cover the processing techniques and design methodologies of microfabrication. We will discuss the process modules: lithography, thermal oxidation, diffusion, ion implantation,	

교과목 포트폴리오 (MEE4088 반도체및MEMS공정개론)

교육과정	관장학과	국문개요	영문개요	수업목표
		etching, thin-film deposition, epitaxy, metallization, MEMS process integration.	etching, thin-film deposition, epitaxy, metallization, MEMS process integration.	
학부 2013 - 2015 교육과정	서울 공과대학 기계공학부	This lecture will cover the processing techniques and design methodologies of microfabrication. We will discuss the process modules: lithography, thermal oxidation, diffusion, ion implantation, etching, thin-film deposition, epitaxy, metallization, MEMS process integration.	This lecture will cover the processing techniques and design methodologies of microfabrication. We will discuss the process modules: lithography, thermal oxidation, diffusion, ion implantation, etching, thin-film deposition, epitaxy, metallization, MEMS process integration.	
학부 2009 - 2012 교육과정	서울 공과대학 기계공학부	This lecture will cover the processing techniques and design methodologies of microfabrication. We will discuss the process modules: lithography, thermal oxidation, diffusion, ion implantation, etching, thin-film deposition, epitaxy, metallization, MEMS process integration.	This lecture will cover the processing techniques and design methodologies of microfabrication. We will discuss the process modules: lithography, thermal oxidation, diffusion, ion implantation, etching, thin-film deposition, epitaxy, metallization, MEMS process integration.	
학부 2005 - 2008 교육과정	서울 공과대학 기계공학부	This lecture will cover the processing techniques and design methodologies of microfabrication. We will discuss the process modules: lithography, thermal oxidation, diffusion, ion implantation, etching, thin-film deposition, epitaxy, metallization, MEMS process integration.	This lecture will cover the processing techniques and design methodologies of microfabrication. We will discuss the process modules: lithography, thermal oxidation, diffusion, ion implantation, etching, thin-film deposition, epitaxy, metallization, MEMS process integration.	

10. CQI 등록내역

No data have been found.